

2

OFFICE OF NAVAL RESEARCH

GRANT: N00014-89-J-1178

TECHNICAL REPORT NO. 63

R&T CODE: 413Q001-05

ELECTRON CYCLOTRON RESONANCE PLASMA AND THERMAL
OXIDATION MECHANISMS OF GERMANIUM

BY
Y. WANG, Y.Z. HU AND E.A. IRENE

DEPARTMENT OF CHEMISTRY
CB#3290 VENABLE
UNIVERSITY OF NORTH CAROLINA
CHAPEL HILL, NC 27599-3290

DTIC
ELECTE
MAR 24 1994
S E D

SUBMITTED TO:

JOURNAL OF VACUUM SCIENCE AND TECHNOLOGY B

REPRODUCTION IN WHOLE OR IN PART IS PERMITTED FOR ANY
PURPOSE OF THE UNITED STATES GOVERNMENT.

THIS DOCUMENT HAS BEEN APPROVED FOR PUBLIC RELEASE AND
SALE; ITS DISTRIBUTION IS UNLIMITED.

248 94-09193
[Barcode]

DTIC QUALITY INSPECTED 1

94-3-23 033

AD-A277 317



REPORT DOCUMENTATION PAGE			Form Approved ONR NO 0704-0188	
<small>Public reporting burden for this collection of information is estimated to average 1 hour per response, including the time for reviewing instructions, searching existing data sources, gathering and maintaining the data needed, and completing and reviewing the collection of information. Send comments regarding this burden estimate or any other aspect of this collection of information, including suggestions for reducing this burden, to Washington Headquarters Services, Directorate for Information Operations and Reports, 1215 Jefferson Davis Highway, Suite 1204, Arlington, VA 22202-4302, and to the Office of Management and Budget, Paperwork Reduction Project (0704-0188), Washington, DC 20503.</small>				
1. AGENCY USE ONLY (Leave blank)		2. REPORT DATE March 15, 1994		3. REPORT TYPE AND DATES COVERED Technical Report #63
4. TITLE AND SUBTITLE Electron Cyclotron Resonance Plasma and Thermal Oxidation Mechanisms of Germanium			5. FUNDING NUMBERS N00014-89-J-1178	
6. AUTHOR(S) Y. Wang, Y.Z. Hu, and E.A. Irene				
7. PERFORMING ORGANIZATION NAME(S) AND ADDRESS(ES) Department of Chemistry University of North Carolina CB #3290 Venable & Kenan Labs Chapel Hill, NC 27599-3290			8. PERFORMING ORGANIZATION REPORT NUMBER N00014-89-J-1178 Technical Report #63	
9. SPONSORING/MONITORING AGENCY NAME(S) AND ADDRESS(ES) Department of Navy Office of Naval Research 800 NorthQuincy Street Arlington, VA 22217-5000			10. SPONSORING/MONITORING AGENCY REPORT NUMBER	
11. SUPPLEMENTARY NOTES Submitted to Journal of Vacuum Science and Technology B				
12a. DISTRIBUTION / AVAILABILITY STATEMENT Reproduction in whole or in part is permitted for any purpose of the United States Government. This document has been approved for public release and sale; its distribution is unlimited.			12b. DISTRIBUTION CODE	
13. ABSTRACT (Maximum 200 words) <p>The electron cyclotron resonance (ECR) plasma oxidation and thermal oxidation mechanisms for germanium were investigated using in-situ spectroscopic and single wavelength ellipsometry. ECR plasma oxidation was performed at substrate temperatures of 80° to 400°C while thermal oxidations were performed between 400° to 600°C. Optical modeling shows that there is an interface between the oxide film and the substrate that is composed of germanium oxide and amorphous germanium. The nature of the interface and factors controlling its thickness were studied for different oxidation conditions and with various characterization methods: X-ray photoelectron spectroscopy (XPS) to confirm the optical model, capacitance-voltage (C-V) measurements to measure electronic properties, and Fourier transform infrared spectroscopy (FTIR) to determine the molecular structure.</p>				
14. SUBJECT TERMS Electron, Cyclotron resonance, thermal oxidations			15. NUMBER OF PAGES	
			16. PRICE CODE	
17. SECURITY CLASSIFICATION OF REPORT Unclassified	18. SECURITY CLASSIFICATION OF THIS PAGE Unclassified	19. SECURITY CLASSIFICATION OF ABSTRACT Unclassified	20. LIMITATION OF ABSTRACT	

ELECTRON CYCLOTRON RESONANCE PLASMA AND
THERMAL OXIDATION MECHANISMS OF GERMANIUM

Y. Wang, Y. Z. Hu and E. A. Irene

Department of Chemistry

University of North Carolina, Chapel Hill, NC 27599-3290

ABSTRACT

The electron cyclotron resonance (ECR) plasma oxidation and thermal oxidation mechanisms for germanium were investigated using in-situ spectroscopic and single wavelength ellipsometry. ECR plasma oxidation was performed at substrate temperatures of 80° to 400 °C while thermal oxidations were performed between 400° to 600 °C. Optical modeling shows that there is an interface between the oxide film and the substrate that is composed of germanium oxide and amorphous germanium. The nature of the interface and factors controlling its thickness were studied for different oxidation conditions and with various characterization methods: X-ray photoelectron spectroscopy (XPS) to confirm the optical model, capacitance-voltage (C-V) measurements to measure electronic properties, and Fourier transform infrared spectroscopy (FTIR) to determine the molecular structure.

Accession For	
NTIS	CRA&I <input checked="" type="checkbox"/>
DTIC	TAB <input type="checkbox"/>
Unannounced <input type="checkbox"/>	
Justification _____	
By _____	
Distribution /	
Availability Codes	
Dist	Avail and / or Special
A-1	

I. INTRODUCTION

Low temperature processing of integrated circuits is of interest, since rates for thermally activated defect production and redistribution of dopants are greatly reduced. Recently low temperature processing techniques^{1,2} have yielded remarkable dielectrics that might one day replace conventional thermal oxidation. Among these techniques electron cyclotron resonance (ECR) plasma offers many important advantages^{3,4} for low damage semiconductor processing, including low ionic energies, high ionization efficiency, low pressure and low temperature operation. Oxygen ECR plasmas have been used to grow SiO₂ from single crystal Si,^{5,6,7,8} exhibiting physical, chemical, and electrical properties similar to those of thermal oxide.

Germanium is an attractive candidate semiconductor for microelectronic technology,^{9,10,11} because the mobility of holes in Ge is larger than any of the other common semiconductors, and the hole and electron mobilities are much less disparate than in other semiconductors. However, it is important to be able to grow a high quality insulator film on the Ge surface in particular at low temperature to avoid the interface decomposition of the oxide, and ECR plasma oxidation of Ge is a candidate to provide a useful process.

In a previous spectroscopic ellipsometry study¹² we reported the GeO₂ film dielectric function from thermally grown GeO₂ films, and ECR plasma oxidation kinetics of Ge.¹³ In the present study both ECR plasma and thermal oxidation of Ge were investigated and compared with respect to the similarities and differences in the oxidation mechanisms, the interface between the oxide and the substrate, and some preliminary electronic properties. In-situ real-time single wavelength ellipsometry (SWE) was used during oxidation, and in-situ static spectroscopic ellipsometry (SE) was performed at various times inside the process vacuum chamber. In order to understand the Ge-GeO₂ interface, some ex-situ analyses were also performed. Electronic properties were examined using high frequency capacitance-voltage (C-V) measurement; X-ray photoelectron

spectroscopy (XPS) was used to establish the chemical species; and transmission Fourier transform infrared (FTIR) spectroscopy was performed to determine the molecular structure.

II. EXPERIMENTAL PROCEDURES

The ECR plasma oxidation apparatus used in this study was described previously.^{14, 15} The system consists of a home-built high precision rotating analyzer spectroscopic ellipsometer and an independent vacuum processing chamber equipped with a homemade ECR plasma source. 2.45 GHz microwaves, as generated by a magnetron, were guided through a quartz window to the ECR plasma chamber into which pure oxygen gas (999.997%) could be flowed. The vacuum chamber can be evacuated to 1×10^{-7} torr using a turbomolecular pump. The Ge substrate to be oxidized is placed on a stainless-steel holder that can be heated using a halogen lamp. The temperature was monitored and controlled using a thermocouple attached to the front side of the holder and adjacent to the sample. A calibration of the holder temperature was made both in comparison with wafer temperature in vacuum for ECR plasma oxidation, and at atmospheric pressure for thermal oxidation.

Samples used were commercially available n-type (100) Ge wafers (resistivity: 20 ohm-cm). All substrates were subjected to a cleaning procedure as described by Aspnes,¹⁶ which consists of 0.05-vol% bromine in methanol etching, followed by a buffered HF cleaning step, and a final deionized water rinsing. ECR plasma oxidation conditions were as follows: total pressure of 1×10^{-3} torr, oxygen flow rate of 20 sccm, microwave power of 300 W, substrate temperature from 25° to 400 °C, and substrate bias voltage from 0 to +60 V.

The oxide growth was monitored by in-situ real-time single wavelength ellipsometry (SWE). Various thicknesses reported in this work were obtained by a trajectory method using a single film

model.^{17, 18} The single wavelength chosen for Ge is 335 nm, because at this wavelength the measurements are insensitive to temperature and very sensitive to oxide growth.¹⁹ Spectroscopic ellipsometry (SE) measurements were taken at 51 photon energies between 2.0 and 4.5 eV, which include two interband transition at 2.3 and 4.4 eV. The SE measurements were taken with the samples inside the vacuum chamber after ECR plasma (or thermal) oxidation. For oxides grown above room temperature, the spectra were obtained after cooling to room temperature.

Thermal oxidations were carried out at 1 atm in pure O₂ in the same system, but without microwave plasma operation through the use of a high vacuum valve between the processing chamber and the turbomolecular pump. Oxygen flow rate was 150 sccm. Substrate temperatures were from 400° to 550 °C. After a cleaned Ge substrate was loaded in the vacuum chamber, the substrate temperature was raised in vacuum. When the substrate reached the desired temperature, the high vacuum valve between processing chamber and the turbomolecular pump was closed. Real-time SWE commenced and then oxygen was admitted into the processing chamber. Upon completion of an oxidation experiment the system was evacuated and SE was performed after cooling the sample to room temperature.

The FTIR technique that we used was discussed by Zettler et al²⁰ wherein IR transmission measurements were carried out at a 75° incident angle with *p*- polarized light using a Fourier-transform infrared spectrometer. Double side polished Ge wafers were used. After ECR plasma or thermal oxidation of Ge, an IR reflective aluminum film was vacuum evaporated on the oxide overlayer. The IR measurement was executed with light incident from back side of the wafer. A spectrum taken from an aluminum mirror using the same setup provided the background spectrum. The transmission spectra were measured in the wavenumber region between 400 and 2000 cm⁻¹.

Au/GeO₂/Ge MOS structures were prepared for C-V measurements. Following oxidation, metal gates, 9x10⁻⁴ cm² in area, were deposited through a shadow mask by evaporating ~1000 Å of Au at 2 Å/sec under a base pressure of 1x10⁻⁷ torr. All the samples received a post metalization anneal at 400°C in Ar for 30 min. Contact was made to the gate with a tungsten probe. Backside contact was made by abrading the wafer and applying a GaIn paste. The 1 MHz high frequency C-V measurements were automated, and interfaced to a personal computer for data acquisition and analysis.²¹

III. EXPERIMENTAL RESULTS

1. Optical modeling

The ellipsometric measurement yields two angles Δ and Ψ , from which the complex reflection ratio ρ_{exp} is obtained: $\rho_{\text{exp}} = \tan \Delta e^{i\Psi}$. From a literature database for the known constituents of the film and substrate, ρ_{cal} is calculated and compared with ρ_{exp} . An unbiased estimator δ is calculated from the relationship:^{17, 22}

$$\delta = \left[\frac{1}{N-P-1} \sum_{i=1}^N |\rho_{\text{exp}} - \rho_{\text{cal}}|^2 \right]^{\frac{1}{2}} \quad (1)$$

where N is the number of wavelengths sampled, and P the number of unknown parameters. A minimizing procedure gives the best fit parameters which are film thickness and volume percentage for the constituents at the 90% confidence level. Previous studies¹³ have shown that a two layer model, composed of pure GeO₂ as the top layer with a thickness of L_{ox} , and an interface layer composed of GeO₂ and a-Ge with a thickness of L_{int} , yields the best fit in terms of the lowest δ .

Table 1 shows the best fit model results for typical thermal and ECR plasma oxidation conditions. For thermal oxidation between 400 °C and 550 °C, there is always a distinct interface layer for different oxidation temperatures and different oxide thicknesses. For ECR plasma oxidation at low temperature, the interface is also clear; but the interface becomes very thin (<1nm) when the substrate temperature was raised to 400 °C at +60 V bias. The interface layer was not observed for +30 V bias.

2. ECR plasma and thermal oxidation kinetics

In order to investigate oxidation kinetics, real time SWE was used to monitor the oxide film growth. Figure 1a and c show the evolution of oxide thickness as a function of oxidation time at different temperatures during the first 20 min of thermal and ECR plasma oxidation, respectively. The data were obtained from real-time SWE measurements analyzed using a single layer model. Figure 1b and d are similar results but were obtained by SE using the two layer model. The total thicknesses ($L_{ox} + L_{int}$) are given by the solid line and the interface thickness (L_{int}) by the filled symbols. The results shown in Figure 1d were obtained from thermal oxidation in a conventional oxidation furnace.²³ Any temperature differences for the two systems were well within 5 °C. For both thermal and ECR plasma oxidation there are three regimes for the relationship between oxide thickness and oxidation time, as we had previously reported¹³: two linear and one parabolic.

For thermal oxidation the second linear and the parabolic regimes are in agreement with the model developed by Deal and Grove(DG),²⁴ which is summarized with the following rate equation:²⁵

$$\frac{L^2 - L_0^2}{k_{P-DG}} + \frac{L - L_0}{k_{L-DG}} = t - t_0 \quad (2)$$

where k_{P-DG} and k_{L-DG} represents the parabolic and linear rate constants in DG model, respectively.

k_{P-DG} is related to diffusion through the oxide while k_{L-DG} reflects the reaction at the Ge surface.

The constants L_0 and t_0 are offsets to the DG model which account for an initial region not explained by the DG model. In the DG model k_{P-DG} corresponds to an elementary, thermally activated diffusion process obeying Boltzman statistics and described by an Arrhenius equation of the form:

$$k_{P-DG} = k_0 \exp(-E_a/k_B T) \quad (3)$$

where k_B is the Boltzman constant, T is the oxidation temperature, and E_a is the activation energy. The linear Arrhenius plot for k_{P-DG} is shown in figure 2a and yield an activation energy of 1.8 eV.

For ECR plasma oxidation, the oxide growth in the first linear region is very fast and virtually bias independent. The parabolic region fits the Cabrera-Mott (CM) model,²⁶ which considers oxidation by charged species in the limit of a low electric field and is given by the relation:

$$L_{ox}^2 = C_1 \exp\left(-\frac{E_a}{k_B T}\right) \frac{V_{ox}}{k_B T} t + C_2 \quad (4)$$

where V_{ox} is the potential drop across the oxide film, E_a is the thermal activation energy associated with the diffusion of oxidizing species in the applied electric field, t is oxidation time, k_B is the Boltzman constant, T is the oxidation temperature, and C_1 and C_2 are constants. The parabolic coefficient k_{P-CM} is given as:

$$k_{P-CM} = C_1 \exp\left(-\frac{E_a}{k_B T}\right) \frac{V_{ox}}{k_B T} \quad (5)$$

In the CM model the parabolic coefficient also follows an Arrhenius expression, and the activation energy calculated from Figure 2b is 0.28 eV.

3. FTIR measurements

Figure 3a and 3b show typical FTIR spectra for thermal and ECR plasma oxidized samples, with the main absorption peak positions summarized in Table 2. The vibrational bands observed in thermal oxide samples are associated with Ge-O-Ge stretching modes (981 cm^{-1} and 859 cm^{-1}) and bending modes (563 cm^{-1} and 521 cm^{-1}) and are in agreement with results from the literature.²⁷⁻²⁹

The IR spectra for thermal and ECR plasma oxides are very similar indicating that the same chemical oxide is obtained by both oxidation methods.

4. XPS results

In the present study, Ge 3d and O 1s spectra of germanium oxide were measured. All binding energies were corrected with C 1s at 285.0 eV. The binding energy for elemental Ge 3d is 29.1 eV from the literature.³⁰ According to Schmeisser,³¹ an average chemical shift per oxidation state for Ge 3d core level is 0.85 eV. This means the chemical shift for GeO₂ is expected to be 3.40 eV and this is observed. For all the samples we have measured, only elemental Ge and GeO₂ were found.

Fig. 4a and 4b show typical XPS spectra of Ge 3d electrons for thermal and ECR plasma oxidation. The two spectra are similar with experimental binding energy and chemical shift Δ of Ge 3d electrons at different oxidation conditions given in table 3. The Ge 3d electron chemical shift for thermal oxidation is 3.45 eV, and a similar value is obtained for ECR plasma oxidation. At 400 °C $\delta\Delta$ is within 0.08 eV relative to that of thermal oxidation. The XPS results are in accord with and support our best fit optical model.

5. High frequency C-V measurements

Figure 5 compares high frequency C-V measurements (1MHz) for similar thickness thermal (solid line) and ECR plasma (dashed line) oxides in a Ge MOS structure. Figure 5a shows that a very thin thermal oxide (3 nm) grown at 400°C yields good interfacial properties (oxide charge density is $\sim 10^{10}$ cm⁻²) but high leakage current as evidenced by the behavior near C_{ox} . The oxide charge density increases as the thickness of the oxide increases. In all the samples measured, the thinner samples displayed smaller interface charge levels (as obtained from the excursion of the C-V trace near flat bands from ϕ_{ms}), but more leakage current. In comparing the C-V curves of

thermal and ECR plasma oxides, it is interesting to note that there is less charge in ECR plasma oxide than in thermal oxide at similar oxide thickness. For the 7 nm oxide, bumps are seen in the depletion region which are likely due to interface states responding to the 1 MHz test frequency³². More extensive oxidation to thicker oxides removes these states. Our purpose in this study is to determine whether the interface is of reasonable quality and what are the differences if any between thermal and ECR plasma oxides. Both kinds of samples show evidence of inversion with a flat C_{min} region when ramped from deep depletion. While the thermal oxides almost always showed more charge near the interface, the thinner thermal oxides were measurable even with leakage while we were unable to perform C-V measurements on ECR plasma oxides that were thinner than 5 nm due to the high currents. However, in neither case has an effort been made to optimize the processes in terms of interfacial electronic properties; the samples were processed identically except for the oxidations.

IV. DISCUSSION AND CONCLUSIONS

First it is seen that the XPS and FTIR data confirm that the oxides resulting from thermal and ECR plasma oxidation are the same, namely GeO_2 . The real time oxidation data and analysis strongly suggest that both thermal and ECR plasma oxidation of Ge follow linear-parabolic kinetics similar to the kinetics proposed for Si thermal oxidation, and both processes display an initially faster regime also similar to Si oxidation. Our previous studies also showed that both Si and Ge ECR plasma oxidation follow linear-parabolic kinetics, and both display an initial bias independent faster oxidation regime.¹³ This initial regime represents the surface reaction between Ge and the plasma oxidant species for ECR plasma oxidation and molecular oxygen for thermal oxidation. For the ECR plasma oxidation the applied substrate bias greatly affects the oxidation

rate after the initial regime and most dramatically when a thicker oxide is formed with positive bias accelerating the rate and negative bias decelerating the rate of film growth. This observation leads to the conclusion that for transport limited growth, negatively charged oxidant species dominate the ECR reaction kinetics. Both thermal and ECR plasma oxidation yield temperature activated transport. However for the ECR plasma oxidation the activation energy is nearly one order of magnitude smaller than for thermal oxidation. This difference can be explained by considering the ECR oxidation via O^- species while thermal oxidation is via molecular species as for the thermal oxidation of Si.²⁵

The best fit optical models for thermal and ECR oxidation are the same two layer model with the top layer being GeO_2 and the interface layer being a-Ge plus GeO_2 . The interesting difference is that for ECR plasma oxidation the interface layer is considerably thinner than for thermal oxidation. In a separate study of the interface region in the Si-SiO₂ system using spectroscopic immersion ellipsometry,^{33,34} we reported that the suboxide layer at the interface increased in thickness as oxidation proceeded, presumably the result of the decreasing oxidant concentration as the overlayer thickens. By analogy to the Ge oxidation system, the rapid transport of O^- species in the ECR process provides a higher oxidant activity at the interface hence a thinner interface region. While further study of this phenomena is warranted and in progress, the smaller interface charge levels observed for ECR plasma oxidation lends further support to this proposition.

VI. ACKNOWLEDGMENTS

The authors are grateful to Mr. W. Ou for XPS measurements and helpful discussions. This work was supported in part by National Science Foundation, NSF and the Office of Naval Research, ONR.

REFERENCES

1. J. Batey and E. Tierney, *J. Appl. Phys.* **60**, 3136 (1986).
2. G. Lucovsky and D. V. Tsu, *J. Vac. Sci. Technol. A* **5**, 2231 (1987).
3. A. Sherman, *Chemical Vapor Deposition for Microelectronics*, Edited by R. F. Bunshah, (Noyes Publications, Park Ridge, NJ, 1987).
4. S. Matsuo, *Handbook of Thin Film Deposition and Technique*, Edited by K. K. Schuegraf, (Noyes Publications, Park Ridge, NJ, 1988).
5. D. A. Carl, D. W. Hess, M. A. Lieberamn, *J. Vac. Sci. Technol. A* **8**, 2924 (1990).
6. D. A. Carl, D. W. Hess, M. A. Lieberamn, T. S. Nguyen, and R. Gronsky, *J. Appl. Phys.* **70**, 3301, (1991).
7. G. T. Salbert, D. K. Reinhard, and J. Asmussen, *J. Vac. Sci. Technol. A* **8**, 2919 (1990).
8. Y. Z. Hu, J. Joseph, and E. A. Irene, *Appl. Phys. Lett.* **59**, 1353 (1991).
9. J. J. Rosenberg and S. C. Martin, *IEEE Electron. Device Lett.* **9**, 639 (1988).
10. Q. Hua, J. J. Rosenberg, J. Ye, and E. S. Yang, *J. Appl. Phys.* **53**, 8969, (1982).
11. D. J. Hymes and J. J. Rosenberg, *J. Electrochem. Soc.* **135**, 961 (1988).
12. Y. Z. Hu, J.-Th. Zettler, S. Chongsawangvirod, Y. Wang, and E. A. Irene, *Appl. Phys. Lett.* **61**(9), 1098 (1992).
13. Y. Z. Hu, Y. Wang, M. Li, J. Joseph, and E. A. Irene, *J. Vac. Sci. Technol. A* **11**(4), 900 (1993).
14. J. W. Andrews, Y. Z. Hu, and E. A. Irene, *SPIE Proc.* **1118**, 162 (1990).
15. J. W. Andrews, Ph.D Thesis, University of North Carolina at Chapel Hill, 1990.
16. D. E. Aspnes, and A. A. Studna, *Appl. Phys. Lett.* **39**, 316 (1981).
17. J. Joseph, Y. Z. Hu, and E. A. Irene, *J. Vac. Sci. Technol. B* **10**(2), 611 (1992).
18. A. Gagnaire, J. Joseph, and A. Etcheberry, *J. Electrochem. Soc.* **134**, 2476 (1987).

19. E. A. Irene, *Thin Solid Films*, **23**, 96, (1993).
20. J.-Th. Zettler, M. Weidner, and A. Roseler, *Phys. Stat. Sol. (a)* **124**, 547 (1991).
21. J. C. Poler, Ph.D. Thesis, University of North Carolina, Chapel Hill, NC, 1992.
22. D. E. Aspnes, J. B. Theeten, and F. Hottier, *Phys. Rev. B* **20**, 3992 (1979).
23. E. A. Lewis and E. A. Irene, *J. Vac. Sci. Technol. A* **4**(3) 916 (1986).
24. B. E. Deal and A. S. Grove, *J. Appl. Phys.* **36**, 3770 (1965).
25. E. A. Irene, *CRC Critical reviews in Solid State and Materials Sciences*, **14**, 175 (1988).
26. N. Cabrera and N. F. Mott, *Rep. Prog. Phys.* **12**, 163 (1948).
27. B. T.-K. Chen and G.-J. Su, *Phys. Chem. Glass.* **12**(1), 33 (1971).
28. M. K. Murthy and E. M. Kirby, *Chem. Glass.* **5**(5), 144 (1964).
29. W. Kaiser, P. H. Keck, and C. F. Lange, *Phys. Rev.* **101**(4), 1264 (1956).
30. G. Hollinger, P. Kumurdjian, J. M. Mackowski, P. Pertosa, L. Porte, and T. M. Duc,
J. Electron. spec. Relat. Phenom. **5**, 237 (1974).
31. D. Schmeisser, R. D. Schnell, A. Bogen, F. J. Himpsel, D. Rieger, G. Landgren, and J. F.
Morar, *Surf. Sci.* **172**, 455 (1986).
32. T. J. Mego, *Solid State Technol.* 159 (May, 1990).
33. Q. Liu and E. A. Irene, *Materials Research Society Symposium Proceedings*, **315**, 405 (1993).
34. Q. Liu, J. F. Wall, and E. A. Irene, submitted to *J. Vac. Sci. Technol. B*

FIGURE CAPTIONS

Figure 1. Oxide thickness vs oxidation time at different temperatures. (a) and (b) are for thermal oxidation while (c) and (d) are for ECR plasma oxidation at +60 V bias. (a) and (c) were obtained from real-time SWE measurements and using a single layer model; (b) and (d) are similar results but were obtained by SE using the two layer model. The total thicknesses are given by the solid lines through the data and the interface thickness by the filled symbols.

Figure 2. Arrhenius plots of the parabolic coefficients for (a) thermal and (b) ECR plasma oxidation.

Figure 3. FTIR spectra of typical (a) thermal oxide at 550 °C; (b) ECR plasma oxide at +60 V bias and 400 °C grown on C-Ge substrates.

Figure 4. XPS spectra of Ge 3d electrons for typical (a) thermal oxide at 550 °C; (b) ECR plasma oxide at +60 V bias and 400 °C grown on C-Ge substrates.

Figure 5. High frequency C-V measurements (1MHz) for different oxide thicknesses: (a) 3 nm oxides; (b) 7 nm oxides; (c) 17 nm oxides. Solid lines are for thermal oxidation and dashed lines for ECR plasma oxidation at +60 V and 400 °C.

TABLE CAPTIONS

Table 1. The best fit optical model results for typical thermal and ECR plasma oxidation conditions. L_{ox} is the top oxide layer thickness. L_{int} is the interface layer thickness. a-Ge% is the volume percentage of amorphous germanium in the interface layer. δ is the unbiased estimator.

Table 2. Absorption peak positions for the IR spectra shown in fig. 3.

Table 3. XPS binding energy and chemical shifts, Δ , for Ge 3d electrons at different oxidation conditions.

Table 1.

Oxidation Conditions		L_{ox} (nm)	L_{int} (nm)	a-Ge%	$\delta \times 10^3$
Thermal Oxidation	400 °C, 120 min.	1.62±0.60	1.43±0.51	27±28	4.72
	500 °C, 125 min.	15.56±0.85	2.09±0.44	47±29	7.89
	550 °C, 120 min.	25.35±0.88	4.76±0.27	30± 8	7.7
ECR Plasma Oxidation	100 °C, 300W, +60V bias, 70 min.	3.77±0.21	2.28±0.16	49± 4	4.58
	400 °C, 300W, +30V bias, 5 min.	7.60±0.16	0	~	5.12
	400 °C, 300W, +60V bias, 40 min.	16.92±0.07	0.82±0.08	31±24	6.19

Table 2.

Vibration Mode	Absorption Peaks (cm ⁻¹) in thermal oxide	Absorption Peaks (cm ⁻¹) in ECR plasma oxide	Absorption Peaks (cm ⁻¹) from literature
Ge-O-Ge Stretching Mode	981	977	820-960 ²⁷ , ~970 ²⁸
	859	853	878 ²⁸ , 887 ²⁹
Ge-O-Ge Bending Mode	563	556	470-595 ²⁷
	521	525	~500-600 ²⁸

Table 3.

Oxidation Conditions		Oxide Thickness (nm)	Binding Energy (Ge 3d, eV)	Chemical Shift Δ (eV)
Thermal Oxidation	550 °C, 10 min	8	29.74, 33.19	3.45
	400 °C, 540 min	3	29.84, 33.30	3.46
ECR plasma Oxidation	300 W, 400 °C, +60 V bias	8	29.71, 33.24	3.53
	300 W, 400 °C, +30 V bias	8	29.78, 33.17	3.39
	300 W, 100 °C, +60 V bias	6	29.45, 33.06	3.61









